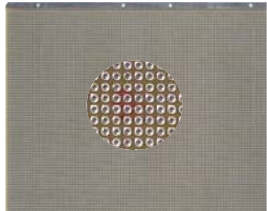


Vectorbord® Circbord™ offers an assortment of basic printed circuit pattern prototyping boards for solder or wire-wrap connections. A wide selection of tin or gold plated terminals and wire-wrap pins located on pages 70-72.

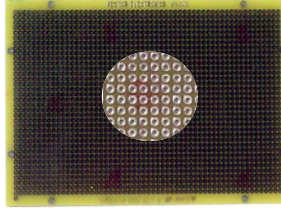
Round Pads-Per-Hole with .025" Holes, .050" Grid



8021 3.94"Hx6.3"Lx .062" TH
(100MM x 160MM)
3U Eurocard size

0.050" grid "M" pattern, 0.024" diameter holes with 0.034" diameter pads, both sides.
Copper plated-thru- holes, solder coated pattern.
Material: FR4
Inbord Pin: K36C

Round Pads-Per-Hole with 0.042" Holes, .100" Grid



8015 4.0"Hx6.0"L x .062" TH

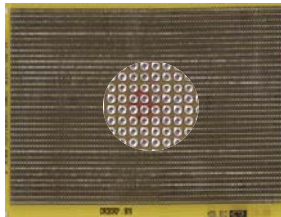
0.100" grid Pad-Per-Hole Pattern. .042" holes plated thru with .080" isolated solder pad around each hole on both sides.
16-Pin DIP= 72.
Material: FR4.
WW Terminals: T44, T46, T49, T68.
Solder Terminals: T42-1, K24C
WW Socket Pin: R32

Strip Busses with 0.042" Holes, .100" Grid



8022 3.0"Hx3.5"L x .062" TH

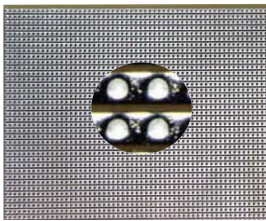
0.100" grid, economical size, 32 stripline tracks (in 3.0" direction), 29 holes per track.
For common bus or signal lines or break pad at any desired number of holes. Copper plated-thru-holes, solder coated pattern.
Material: FR4
WW Terminals: T44, T46, T49, T68
Solder Terminals: T42-1
WW Socket Pin: R32



8010 4.0"Hx13.0"L x .062" TH

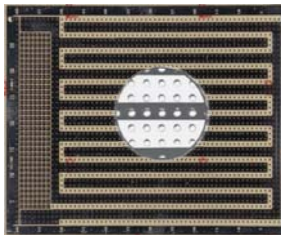
0.100" grid Pad-Per-Hole Pattern on component side- overall Ground Plane pattern on wiring side. .042" holes plated thru with .080" isolated solder pad around each hole on both sides.
16-Pin DIP= 124. Material: FR4.
WW Terminals: T44, T46, T49, T68.
Solder Terminals: T42-1
WW Socket Pin: R32

Strip Busses with 0.042" Holes, .100" Grid



8019 3.94"H x 6.3"L x .062" TH
3U Eurocard size

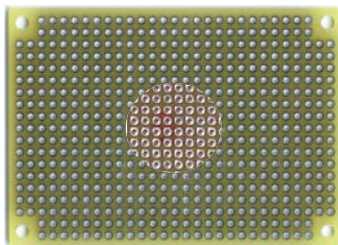
0.100" grid, economical size, 38 lengthwise stripline tracks (in 6.3" direction), 64 holes per track. For common bus or signal lines, or break pad at any desired number of holes.
Copper plated-thru-holes, solder coated pattern.
Material: FR4
WW Terminals: T44, T46, T49, T68
Solder Terminals: T42-1
WW Socket Pin: R32



8002 4.5"Hx6.5"L x .062" TH

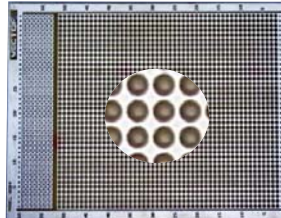
0.100" grid Interleave Bus Pattern on one side only, no plating or etch on reverse side. Components can be mounted on 0.3", 0.6" and 0.9" lead spacing. 0.042" holes with Power/GND busses. I/O area with square pads for connector mounting.
Solder coated pattern.
Material: CEM-1
WW Terminals: T44, T46, T49, T68.
Solder Terminals: T42-1
WW Socket Pin: R32

Round Pads-Per-Hole with 0.042" Holes, .100" Grid



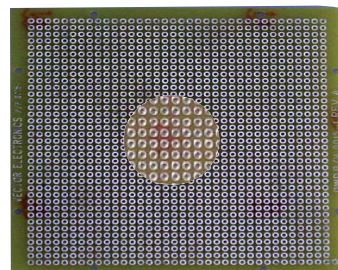
8029 2.0"Hx3.0"L x .062" TH

0.100" grid, Pad-Per-Hole Pattern on both sides, 0.042" holes plated-thru copper.
Small economical size ideal for mounting on standoffs. Solder coated pattern.
16-Pin DIP capacity = 24
Material: FR4
WW Terminals: T44, T46, T49, T68
Solder Terminals: T42-1
WW Socket Pin: R32



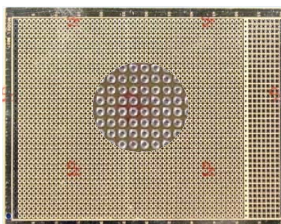
8004 4.50"Hx6.50"Lx.062"TH

0.100" grid single sided w/overall Ground Plane only Single-sided with no etch & plating on reverse side
.042" holes with .080" clearance around each hole. I/O area w/square solder pads for mounting connector
16-Pin DIP = 50
Material: FR-4
WW Terminals: T44, T46, T49, T68
Solder Terminals: T42-1
WW Socket Pin: R32



8015-1 4.0"Hx4.0"L x .062" TH

0.100" grid Pad-Per-Hole 1 sided Pattern
No etch or plating on reverse side
.042" holes with isolated round pad around each hole
16-Pin DIP= 72
Material: FR4
WW Terminals: T44, T46, T49, T68
Solder Terminals: T42-1, K24C
WW Socket Pin: R32



8007 4.50"Hx6.50"L x .062" TH

0.100" grid Pad-Per-Hole Pattern on component side - overall Ground Plane pattern on wiring side .042" holes not plated thru with .080" isolated solder pad I/O area w/square solder pads for mounting connector
16-Pin DIP= 60
Material: CEM-1
WW Terminals: T44, T46, T49, T68
Solder Terminals: T42-1
WW Socket Pin: R32